

产 品 规 格 书

SPECIFICATIONS FOR PRODUCT

产品类型 TYPE : SMD3225

产品规格 SPEC : 27MHz/3225/20PF/10PPM

产品型号 P/N : CJ13-270002010A10

日期 DATE : 2018/12/05

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|----------------------|-------------------|-------------------|-----------|
| 核准及签名 | | | 部门 |
| R&D APPR. SIGNATURED | | | DEPT. |
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SMCE3225 4 pads Crystal Resonator

CJ13-270002010A10

1. Scope:

- 1.1 This specification applies to the RoHS/SONY compliance quartz crystal unit with a frequency of 27MHz which will be used in crystal oscillator applications.

2. Construction:

- 2.1 Type of Quartz Resonator: SMCE3225 4pads

3. Electrical Characteristics

- 3.1 Nominal Frequency(f): 27MHz
- 3.2 Load Capacitance(C_L): 20pF
- 3.3 Frequency Tolerance($\Delta f/f$): ± 10 ppm
- 3.4 Frequency Temperature Stability: ± 10 ppm
- 3.5 Resonance Resistance(ohm): 60ohms Max
- 3.6 Osc mode: Fundamental mode
- 3.7 Shunt Capacitance(C_0): < 2 pF
- 3.8 Drive Level(D_L): $< 100\mu W$
- 3.9 Operating Temperature Range(T_{OPR}): -20 to + 70
- 3.10 Storage Temperature Range(T_{STG}): -55 to + 125°C
- 3.11 Insulation Resistance(IR): > 500 M ohms
- 3.12 Aging(Δf_A): ± 3 ppm per Year

4. Reliability Specifications

This is the quality control and quality assurance and reliability tests performance data for the RoHS/

SONY compliance 27MHz SMCE3225 4pads crystal resonators

related to the specification and approval sheet provided by JSCJ .

Standard test condition (TEMP.: 20±5°C. Relative humidity: 65±20%)

For any discrepancy in GO/NG, test will be done at TEMP.25±2°C, R.H. 65±5%.

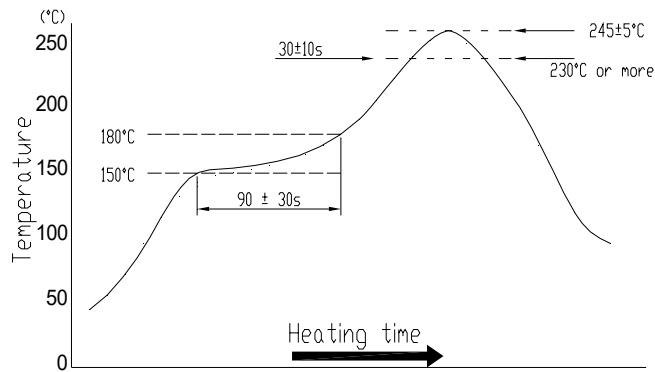
| NO. | PROCESS | SPECIFICATION | TEST METHOD |
|------|--|--|---|
| 4.1 | Temperature Cycle (GB/T 2423.22-2002, Method Nb) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. | 10 cycles from -55°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours. |
| 4.2 | Low Temperature Storage (GB/T 2423.1-2001, Method Aa) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. | Spending 72 hrs at -55°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours. |
| 4.3 | High Temperature Storage (GB/T 2423.2-2001, Method Ba) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. | Spending 72 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours. |
| 4.4 | Humidity (GB/T 2423.3-2006, Method Cab) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. | Spending 96 hrs at 40 °C ± 3 °C, with 93 %R.H, Then keep the DUT in dry oven at 40 ± 5 °C for 24 hour. Measurement taken after DUT being left at room temperature for 1 to 2 hours. |
| 4.5 | Vibration (GB/T 2423.10-1995, Method Fc) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. | Apply 0.75mm vibration at sweep frequency 10~500 Hz, 10 cycles in each direction of 3 axis. Measurement taken after 1 hour. |
| 4.6 | Shock (GB/T 2423.5-1995, Method Ea) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. and exhibit no visible damage. | Peak 1000m/s ² , normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour. |
| 4.7 | Drop (GB/T 2423.8-1995, Method Ed) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. and exhibit no visible damage. | Free drop to the steel plate with thickness of 3 mm from 1.00 m heights for 3 times. |
| 4.8 | Solderability (IEC60068-2-58, Test Td:) | Terminals shall be covered more then 95% with solder. | Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 20s ± 5s at 235°C, peak soldering time for 10s ± 1s between 240 and 250°C. There is no need to do functional test. 8-12X magnifier. |
| 4.9 | Terminal Strength (JIS-C-6429 Method 1 & 2) | No visible damage | Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 1.8kg for at least 60 seconds. |
| 4.10 | Resistance to Soldering Heat (IEC60068-2-58, Test Td: Table 4) | Frequency change after test ± 5 ppm. Resonance resistance change after test ≤ 10 ohms. | Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 60s max at 235°C, peak soldering time for 20s max at 265°C max. Measurement taken after DUT being left at room temperature for at least 2 hours. |
| 4.11 | OTHERS | | |

Recommended Reflow soldering conditon

5. Recommended Reflow soldering condition (SMD)

Solder profile

Peak: $245\pm 5^{\circ}\text{C}$ Soldering zone: 230°C or more, $30\pm 10\text{s}$. Pre-heating zone 1: $150\sim 180^{\circ}\text{C}$, $90\pm 30\text{s}$

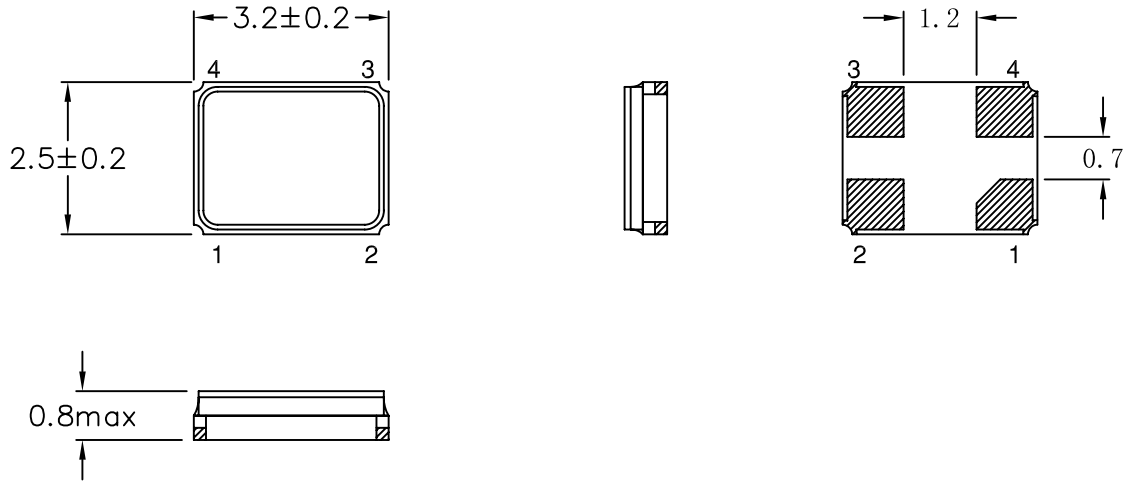


Temperature profile for reflow soldering

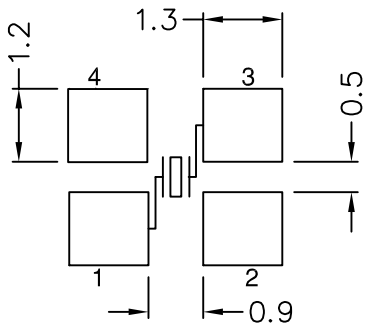
6. Soldering iron method

Bit temperature: $350\pm 10^{\circ}\text{C}$ Application time of soldering iron: $3+1\text{ s}$. For other procedures, refer to IEC 60068-2-20.

Package Outline Dimensions

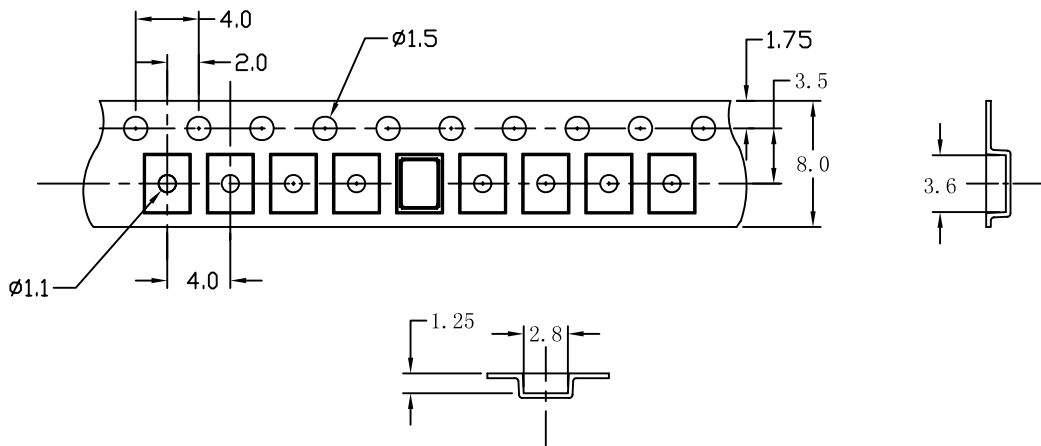
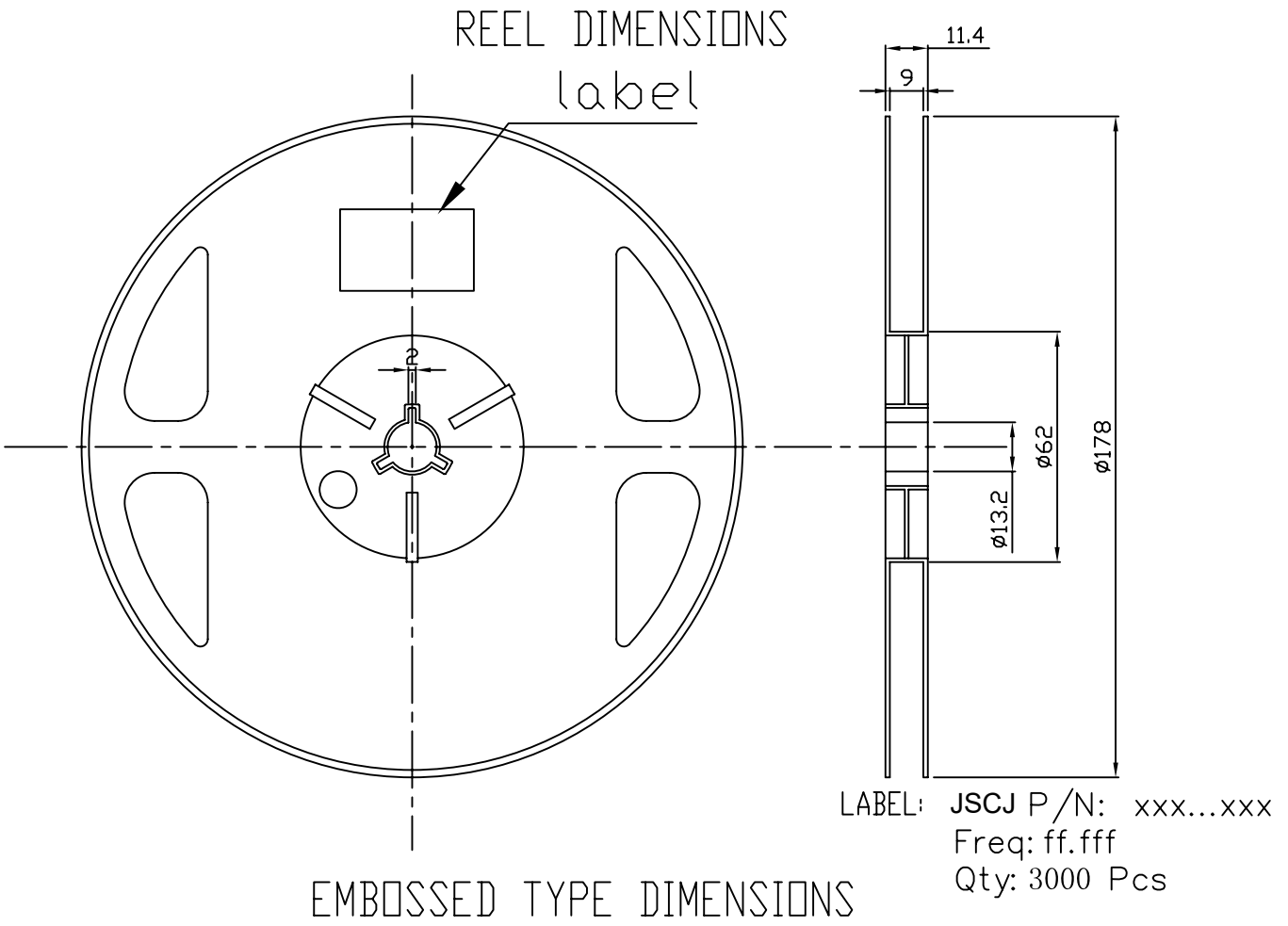


Suggested Pad Layout



NOTICE

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USER FEED DIRECTION

